

電化學沈積之間隙寬度偵測研究

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摘要

本研究於深孔放電加工機台上實行局部電化學沉積，並偵測局部電化學沉積反應之各種特性。主要探討在於各種不同條件參數下，局部電化學沉積之間隙寬度的變化量，並找出最適合的參數條件來完成沉積結構。文中會詳細討論電壓、電流、電阻、及間隙等各種條件間的關係，以及如何設計局部電化學沉積之間隙寬度偵測感測器，來做整個間隙控制迴路之回授訊號控制。

關鍵詞：放電加工機；局部電化學沈積；間隙控制

目錄

第一章 緒論 1.1 前言 1.2 研究動機 1.3 論文架構 第二章 系統架構回顧 2.1 富士可程式控制器 2.1.1 撰寫語言 2.2 可變焦顯微放大擷取觀察系統 2.3 電化學 第三章 硬體設計與模擬 3.1 感測器之設計 3.2 電解液之調配 3.3 電解槽之設計 3.4 電壓補償 3.5 系統模擬 第四章 結果與討論 4.1 電化學沉積參數設定 4.1.1 相同限流電 4.1.2 相同參考電壓 4.2 沉積速度曲線圖 第五章 結論與未來展望 5.1 結論 5.2 未來展望 參考文獻

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